

Amendments to the Specification

Please replace the title with the following amended title:

~~SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF~~
INCLUDING A PROTECTIVE BACKING RESIN LAYER

***Please replace the paragraph inserted between the title and the heading
“BACKGROUND OF THE INVENTION”, with the following amended paragraph:***

CROSS REFERENCE TO RELATED APPLICATIONS

This is a divisional application of application Serial No. 09/878,375, filed June 12, 2001, now U.S. Patent No. 6,734,092, which is a divisional application of Serial No. 09/497,684 filed February 4, 2000, now U.S. Patent No. 6,271,588, which are hereby incorporated by reference in their entirety for all purposes.